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PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

April 20, 2009

Applicants: Atsushi YABE et al
For: ELECTROLESS COPPER PLATING SOLUTION
Serial No.: 10/576 231 Group: 1792
Confirmation No.: 7188
Filed: April 14, 2006 Examiner: Bareford
International Application No.: PCT/JP2004/011327
International Filing Date: July 30, 2004
Atty. Docket No.: 4700.P0327US

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

LETTER TO PATENT OFFICE

Sir:

Further to the Request for Continued Examination filed February 20, 2009, Applicants are enclosing herewith a Declaration Under 37 CFR 1.132 in which additional tests are performed that illustrate the importance of the water-soluble nitrogen-containing polymer being present in the electroless copper plating solution of the present invention. In order to show that the presently claimed invention is not limited to polyethylene amine and polyacrylamide as the water-soluble nitrogen-containing polymer as it uses polyvinyl pyrrolidone as the water-soluble nitrogen-containing polymer and produces excellent results. Example 8 in the enclosed Declaration shows that the electroless copper plating solution can be used to deposit copper on substrates other than a silicon wafer having a tantalum nitride film and still produce excellent results.

Reconsideration of the present application is respectfully solicited.

Respectfully submitted,


Terryence F. Chapman

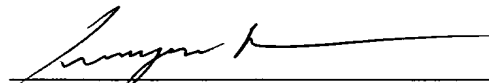
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Encl: Declaration Under 37 CFR 1.132
Postal Card

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on April 20, 2009.


Terryence F. Chapman

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